DESCRIPTION

Title of Invention: SUBSTRATE DESCRIPTION APPARATUS

Technical Field

[0001]

The present disclosure relates to a substrate processing apparatus.

Background Art

[0002]

PTL 1 discloses a substrate processing apparatus in which processing modules are connected to a vacuum transfer module. An example of the substrate processing apparatus has a configuration in which a first vacuum transfer module and a second vacuum transfer module are coupled, and six processing modules are connected to each vacuum transfer module.

Citation List

Patent Literature

[0003]

PTL 1: JP2022-104056A

Summary of Invention

Technical Problem

[0004]

The technique according to the present disclosure improve the production efficiency of a substrate processing apparatus.

Solution to Problem

[0005]

An aspect of the present disclosure is a substrate processing apparatus for processing a substrate, the substrate processing apparatus having: composite modules in each of which one transfer chamber having a transfer space for the substrate and a processing chamber having a processing space for the substrate are integrated, in which the composite modules are connected by connecting the transfer chambers adjacent to each other.

Advantageous Effects of Invention

[0006]

According to the present disclosure, it is possible to improve the production efficiency of the substrate processing apparatus.

Brief Description of Drawings

[0007]

[FIG. 1] FIG. 1 is a perspective view illustrating a schematic configuration of a wafer processing apparatus according to the present embodiment.

[FIG. 2] FIG. 2 is a plan view illustrating a schematic configuration of the wafer processing apparatus according to the present embodiment.

[FIG. 3] FIG. 3 is a view schematically illustrating a schematic configuration of a composite module.

[FIG. 4] FIG. 4 is a view schematically illustrating a schematic configuration of both end surfaces of a transfer chamber.

[FIG. 5] FIG. 5 is a plan view illustrating a schematic configuration of a transfer unit.

[FIG. 6] FIG. 6 is a side view illustrating a schematic configuration of the composite module.

[FIG. 7] FIG. 7 is a view illustrating a state of producing the wafer processing apparatus.

[FIG. 8] FIG. 8 is a plan view illustrating a schematic configuration of a wafer processing apparatus according to another embodiment.

[FIG. 9] FIG. 9 is a plan view illustrating a schematic configuration of a wafer processing apparatus according to another embodiment.

[FIG. 10] FIG. 10 is a plan view illustrating a schematic configuration of a wafer processing apparatus according to another embodiment.

[FIG. 11] FIG. 11 is a plan view illustrating a schematic configuration of a wafer processing apparatus according to another embodiment.

[FIG. 12] FIG. 12 is a plan view illustrating a schematic configuration of a wafer processing apparatus according to another embodiment.

[FIG. 13A] FIG. 13A is a plan view illustrating a schematic configuration of a wafer processing apparatus in the related art.

[FIG. 13] FIG. 13B is a plan view illustrating a schematic configuration of the wafer processing apparatus in the related art.

[FIG. 13] FIG. 13C is a plan view illustrating a schematic configuration of the wafer processing apparatus in the related art.

[FIG. 13] FIG. 13D is a plan view illustrating a schematic configuration of the wafer processing apparatus in the related art.